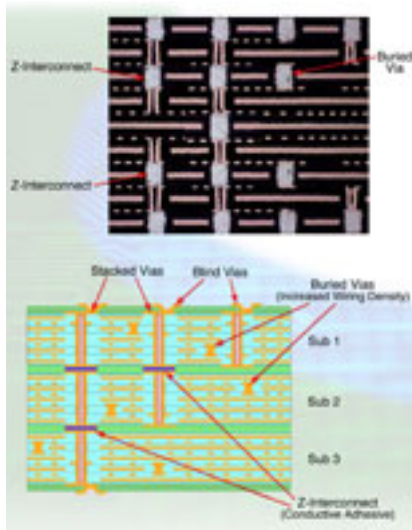


HPC-Z Interconnect



Endicott Interconnect Technologies introduces an HPC-Z interconnect, which provides signal connections only where desired, with functional isolation for single- or double-side surface mount partitions. The HPC-Z interconnect solves thick board drilling and wire density problems, and meets the need for functional isolation, with the capability of isolating high-speed channels on one sub-assembly and low-speed channels on another. HPC-Z provides a “PTH-like” connection at lamination with a pad-to-pad connection made with conductive epoxy. Since there is vertical connection with a lamination in place of a PTH, aspect ratios for drill and plate are limited to sub-assembly dimensions.

www.endicottinterconnect.com 866-820-4820

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<http://www.wirelessdesignmag.com/product-releases/2007/07/hpc-z-interconnect>